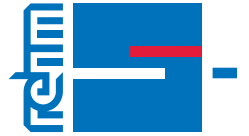
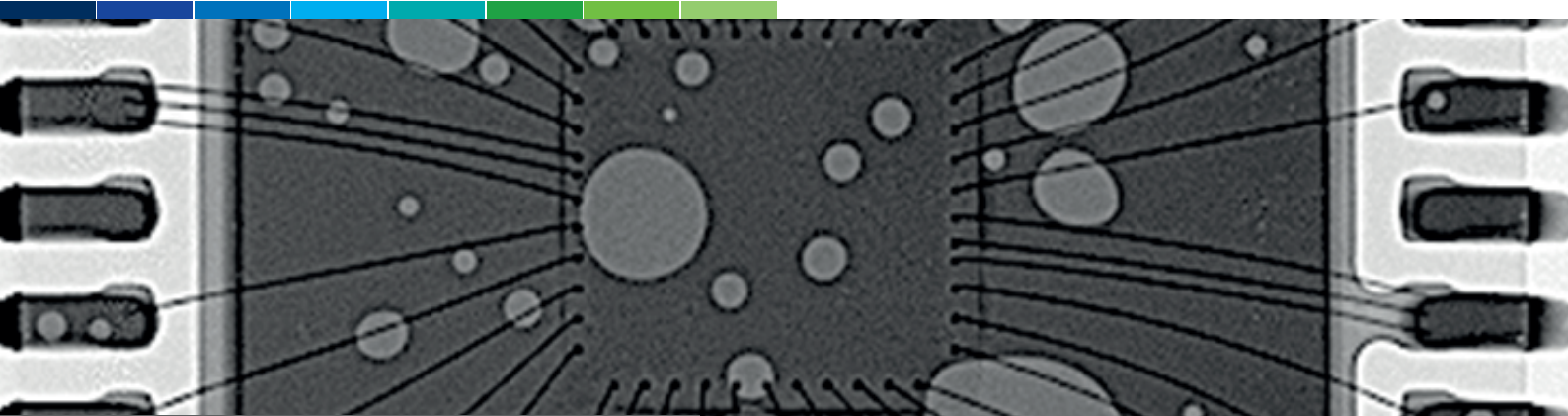


WEBINAR

Reduction of Void Formation with Vacuum



THERMAL SYSTEMS



July 31, 2025 at 9:00 a.m. and 4:00 p.m.

Vacuum soldering has been a proven technique for decades in conductive heat and vapour phase soldering systems, significantly reducing gasbubbles in solder joints. But what is the effect in combination with convection soldering? Today convection soldering is the most popular soldering method in electronic productions with highest throughput.

In our webinar we explain the possibilities of different vacuum soldering processes and also show the corresponding limits.

July 31, 2025 9.00 a.m. CEST (for Asia, Europe, ROW)
4:00 p.m. CEST (for Americas, Europe)

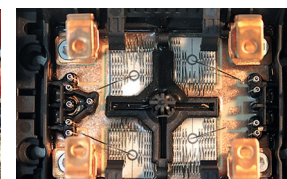
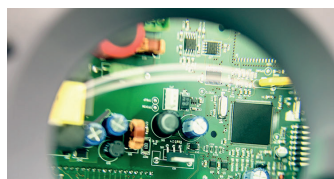
Registration:
i.zielke@rehm-group.com

Duration of the webinar: 60 min

Main topics of the webinar

- Basics of void formation:
Influence of material and process parameters
- Acceptance criteria of void contents –
Guidelines and Standards
- Effect of vacuum:
Reduction of void contents
- Comparison of soldering systems with vacuum:
Convection, Condensation and Conductive heat
- Q&A

Subject to substantive adjustments



TECHNOLOGY ACADEMY